

S/N 10/606,539

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al. Examiner: James Mitchell
Serial No.: 10/606,539 Group Art Unit: 2833
Filed: June 26, 2003 Docket: 303.533US2
Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC
COOLING

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

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Dkt: 303.533US2

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6904

Date Jan. 12, 2005

By Daniel J. Kluth
Daniel J. Kluth
Reg. No. 32,146

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 12 day of January, 2005.

Name

KACIA LEE

Signature

Kacia Lee



Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Complete if Known		Application Number	10/606,539
		Filing Date	June 26, 2003
		First Named Inventor	Ahn, Kie
		Group Art Unit	2833
		Examiner Name	Mitchell, James
Sheet 1 of 1		Attorney Docket No: 303.533US2	

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-6,821,802	11/23/2004	Ahn, K. Y., et al.	08/22/2001

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²

EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached



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Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC
COOLING

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/144290 6281042	August 31, 1998	303.494US1	STRUCTURE AND METHOD FOR A HIGH PERFORMANCE ELECTRONIC PACKAGING ASSEMBLY
09/924303 6570248	August 8, 2001	303.494US2	STRUCTURE AND METHOD FOR A HIGH PERFORMANCE ELECTRONIC PACKAGING ASSEMBLY
09/144307 6586835	August 31, 1998	303.533US1	COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING
09/143880 6392296	August 31, 1998	303.535US1	SILICON INTERPOSER WITH OPTICAL CONNECTIONS
09/935233 6821802	August 22, 2001	303.535US2	SILICON INTERPOSER WITH OPTICAL CONNECTIONS
09/143729 6219237	August 31, 1998	303.536US1	STRUCTURE AND METHOD FOR AN ELECTRONIC ASSEMBLY
09/836564 6496370	April 17, 2001	303.536US2	STRUCTURE AND METHOD FOR AN ELECTRONIC ASSEMBLY

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/606,539

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Filing Date: June 26, 2003

Dkt: 303.533US2

Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING

10/728110

December
4, 2003

303.535US3

SILICON INTERPOSER WITH
OPTICAL CONNECTIONS

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6904

Date Jan. 12, 2005

By

Daniel J. Kluth

Daniel J. Kluth
Reg. No. 32,146

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 12 day of January, 2005.

Name

KACIA LEE

Signature

Kacia Lee